In Re Application Of: K. Sahota, D. Schonauer, J. Groschopf, G. Marxsen, and S. Avanzino Serial No. Filing Date Examiner Group Art Uni 09/749,191 Dec. 26, 2000 L. Umez-Eronini 1765 Invention: Prevention of Precipitation Defects on Copper Interconnects During CMP By Use of Solutions Containing Organic Compounds With Silica Adsorption and Copper Corrosion Inhibiting Properties					
09/749,191 Dec. 26, 2000 L. Umez-Eronini 1765 Invention: Prevention of Precipitation Defects on Copper Interconnects During CMP By Use of Solutions Containing					
Invention: Prevention of Precipitation Defects on Copper Interconnects During CMP By Use of Solutions Containing Organic Compounds With Silica Adsorption and Copper Corrosion Inhibiting Properties					
Organic Compounds With Silica Adsorption and Copper Corrosion Inhibiting Properties					
Organic Compounds With Silica Adsorption and Copper Corrosion Inhibiting Properties					
Attention: Office of Petitions COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, VA 22313-1450					
NOTE: If information or assistance is needed in completing this form, please contact Petitions Information at (703) 305-9282.					
The above-identified application became abandoned for failure to file a timely and proper response to a notice or action by the Patent and Trademark Office. The date of abandonment is the day after the expiration date of the period set for reply in the Office notice or action plus any extension of time actually obtained.					
APPLICANT HEREBY PETITIONS FOR REVIVAL OF THIS APPLICATION					
NOTE: A grantable petition requires the following items: (1) Petition fee; (2) Reply and/or issue fee; (3) Terminal disclaimer with disclaimer feerequired for all utility and plant applications filed before June 8. 1995; and for all design applications; and (4) Statement that the entire delay was unintentional.					
1. A proposed reply to the above-identified notice or action:					
☑ is enclosed. ☐ was filed on					
The proposed reply is in the form of: Notice of Foreign Filling					
2. The issue fee: is enclosed. was paid on					
The abandoned application was a: □ design application. □ plant application.					
4. A terminal disclaimer (and fee) disclaiming a period equivalent to the period of abandonment is enclosed.					
5. Since this utility/plant application was filed on or after June 8, 1995, no terminal disclaimer is required.					

Pe	tition For Re	rival Of An Application For Pa ally Under 37 CFR 1.137(b) (I	atent Ahandanad		
<u> </u>	Docket No. E0520CIP				
In Re Application Of: K. Sahota, D. Schonauer, J. Groschopf, G. Marxsen, and S. Avanzino					
Seri	Serial No. Filing Date Examiner		Group Art Unit		
09/749,191		Dec. 26, 2000	L. Umez-Eronigi	1765	
Invention: Organic Co	Prevention o	f Precipitation Defects on Copper Silica Adsorption and Copper Co	Interconnects During CMP By Unorrosion Inhibiting Properties	se of Solutions Containing	
Calculation and Payment of Fees					
Enclosed are	the following	fees:			
6. Petition fee under 37 CFR 1.17(m) in the amount of:					
7. Fee for amendment in the amount of:					
8. Fee for extension of time to respond to Office Action in the amount of:					
9. Issue fee in the amount of:					
10. Continuing application filing fee in the amount of:					
11. 🔲 Ter	minal disclaim	er fee in the amount of:			
12. 🗆					
			Total fees en	nclosed: \$1,300.00	
🖄 The Di		is to be paid as follows: Int of the fee is enclosed. In authorized to charge any fees CREDIT CARD	which may be required, or credit a	any overpayment, to	

Petition For Revival Of An Application For Patent Abandoned Unintentionally Under 37 CFR 1.137(b) (Large Entity)

Docket No. E0520CIP

In Re Application Of: K. Sahota, D. Schonauer, J. Groschopf, G. Marxsen, and S. Avanzino

Serial No. 09/749,191

Filing Date Dec. 26, 2000

Examiner
L. Umez-Eronini

Group Art Unit

Invention: Prevention of Precipitation Defects on Copper Interconnects During CMP By Use of Solutions Containing Organic Compounds With Silica Adsorption and Copper Corrosion Inhibiting Properties

Statement

The entire delay in filing the required reply from the due date for the required reply until the filing of a grantable petition under 37 CFR 1.137(b) was unintentional.

Weller W. Wellow Dated;

Deborah W. Wenocur, Reg. No. 40,221 Agent for Applicant Advanced Micro Devices, Inc., Technology Law Dept. One AMD Place, M/S 68 P.O. Box 3453 Sunnyvale, CA 94088-3453

I certify that this document and fee is being deposited on with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Mall Stop Petition, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Signature of Person Mailing Correspondence

Deborah W. Wenocur

Typed or Printed Name of Person Mailing Correspondence

CC: